

产品规格书

Specifcation of products

产品名称: 整流管模块

产品型号: MDC90A-M1

浙江世菱半导体有限公司
ZHEJIANG SHILING SEMICONDUCTOR CO.,LTD.

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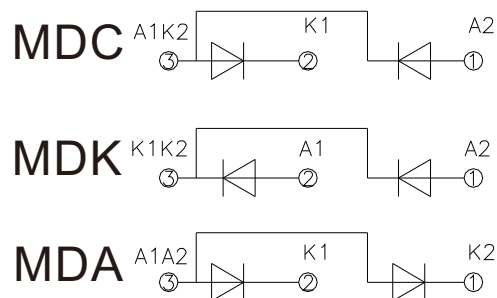
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拟制	审核	核准
林益龙	曹剑龙	宗瑞

SYMBOL	CHARACTERISTIC	TEST CONDI TIONS	T _j (℃)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled,T _C =100℃	150		90		A
I _{F(RMS)}	RMS forward current	Single side cooled,T _C =100℃	150		141		A
V _{RRM}	Repetitive peak reverse voltage	V _{RRM} tp=10ms V _{RSM} = V _{DRM} &V _{RRM} +200V	150	600		1800	V
I _{RRM}	Repetitive peak current	at V _{RRM}	150			5	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			2. 50	KA
I ² t	I ² T for fusing coordination	V _R =0. 6V _{RRM}				31. 25	A ² s*10 ³
V _{FO}	Threshold voltage		150			0. 80	V
r _F	Forward slop resistance					1. 70	m Ω
V _{FM}	Peak forward voltage	I _{FM} =300A	25		1. 3		V
R _{th(j-c)}	Thermal resistance Junction to heatsink	At 180° sine Single side cooled				0. 350	℃ /W
V _{iso}	Isolation voltage	50Hz, RM. S, t=1min, I _{iso} = 1mA (max)		3000			V
F _m	Terminal connection torque(M5)				5. 0		N.m
	Mounting torque(M6)				5. 0		N.m
T _{stg}	Stored temperature			-40		125	℃
W _t	Weight				100		g
Outline							

OUTLINE DRAWING & CIRCUIT DIAGRAM



Rating and Characteristic

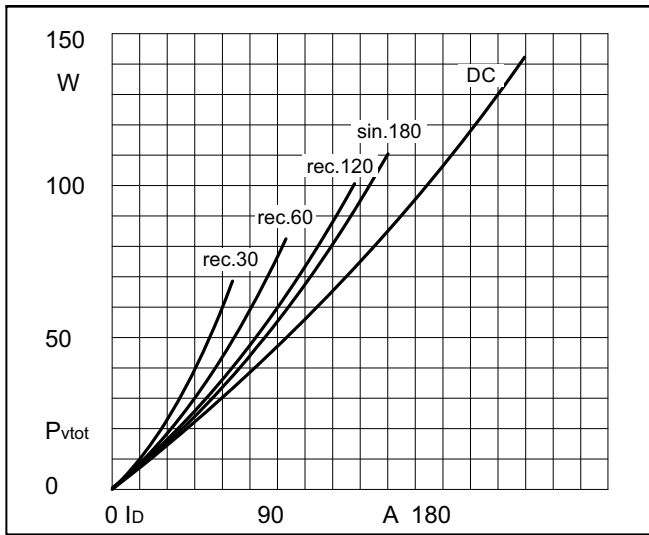


Fig1. Power dissipation

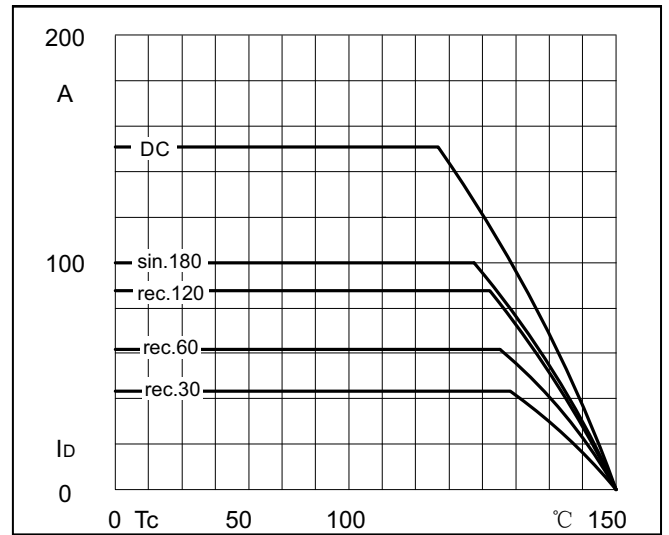


Fig2. Forward Current Derating Curve

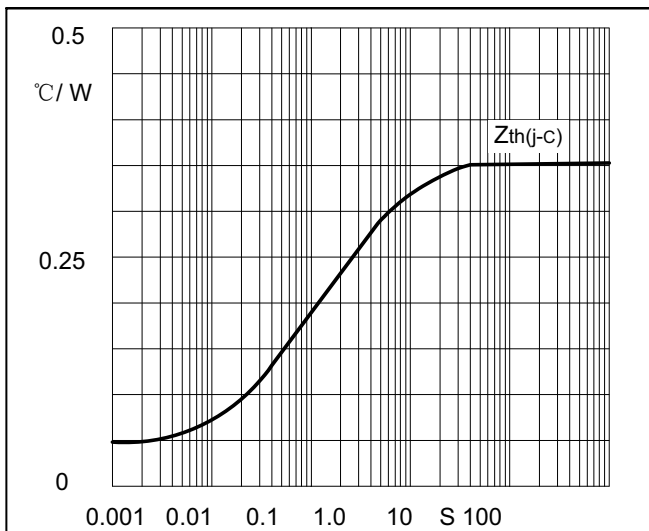


Fig3. Transient thermal impedance

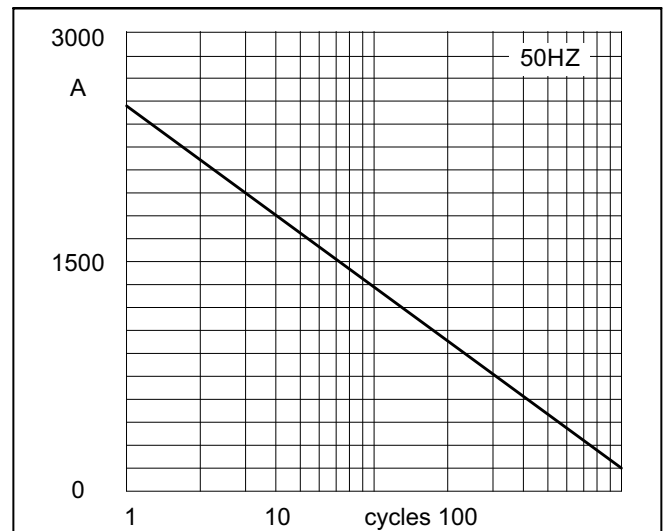


Fig4. Max Non-Repetitive Forward Surge Current

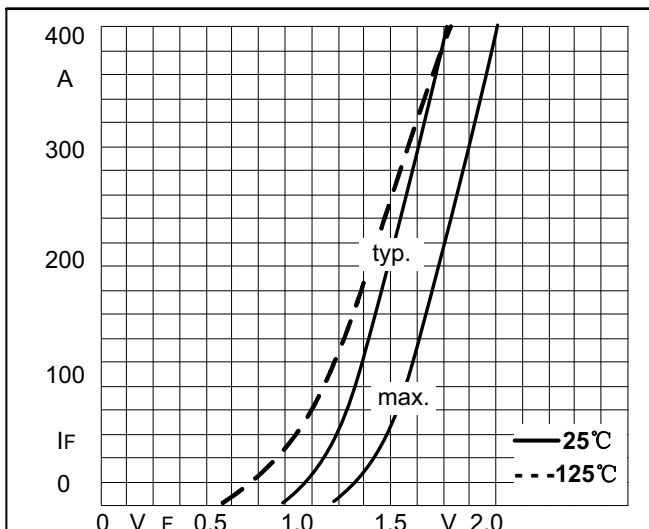


Fig5. Forward Characteristics

Outside Dimension

